

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/10/2022

Details for "TPIC6A259DW"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TPIC6A259DW	NIPDAU	Level-1-260C-UNLIM	TI TAIWAN A/T	DW 24	7.52x15.36x2.35	680.8

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Other Nonferrous Metals and Alloys	Lanthanum	7439-91-0	0.000001	0.000176	2	0	0
Precious Metals	Gold	7440-57-5	0.569254	99.999473	999995	0.083616	836
Precious Metals	Silver	7440-22-4	0.000002	0.000351	4	0	0
Sub-Total			0.569257	100	1000000	0.083617	836
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	1.037913	80.000015	800000	0.152456	1525
Thermoplastics	Epoxy	85954-11-6	0.259478	19.999985	200000	0.038114	381
Sub-Total			1.297391	100	1000000	0.19057	1906
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	155.662748	97.425	974250	22.86489	228649
Copper and Its Alloys	Iron	7439-89-6	3.834648	2.4	24000	0.563261	5633
Copper and Its Alloys	Phosphorus	7723-14-0	0.023967	0.015	150	0.00352	35
Copper and Its Alloys	Tin	7440-31-5	0.047933	0.03	300	0.007041	70
Copper and Its Alloys	Zinc	7440-66-6	0.159777	0.1	1000	0.023469	235
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.047933	0.03	300	0.007041	70
Sub-Total			159.777006	100	1000000	23.469223	234692
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.212118	95.120179	951202	0.031157	312
Precious Metals	Gold	7440-57-5	0.001739	0.779821	7798	0.000255	3
Precious Metals	Palladium	7440-05-3	0.009143	4.1	41000	0.001343	13
Sub-Total			0.223	100	1000000	0.032756	328
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	452.923423	88	880000	66.528727	665287
Other Plastics and Rubber	Carbon Black	1333-86-4	1.544057	0.3	3000	0.226802	2268
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	2.830771	0.55	5500	0.415804	4158
Thermoplastics	Epoxy	85954-11-6	57.387456	11.15	111500	8.429492	84295
Sub-Total			514.685707	100	1000000	75.600825	756008
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	4.241405	100	1000000	0.623009	6230
Sub-Total			4.241405	100	1000000	0.623009	6230
Total			680.793766			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/eoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.